

1

9.00

3

min.6

10

1.2^{+0.05}_{-0.10}

4

3.6

2

2.00

• (3.2^{+0.1}_{-0.3})

6

4.0

1.50

STE

STE

A

A

0.6±0.03

7

(10.5)

PCB

0.80

2.30

(3.1^{+0.1})

(1.6±0.2)

A-A

20:1

1.24±0.08

PCB-LAYOUT

Leiterplatten-Layout

5

2±0.05

NOTES:

BEMERKUNGEN:

1

1.27 μm - 2.54 μm Ni OVER THE COMPLETE LENGTH

1.27 μm - 2.54 μm Ni ueber die gesamte Laenge

2

0.8 μm - 1.8 μm Sn

0.8 μm - 1.8 μm Sn

3

1.0 μm - 3.0 μm Sn

1.0 μm - 3.0 μm Sn

4

Sn

Sn

5

RESTRING

UEBERSTAND

MIN. 50 μm

PLATED THROUGH HOLE SPECIFICATION

SPEZIFIKATION FUER DURCHPLATIERTE BOHRUNGEN

Cu THICKNESS KUPFER-SCHICHTDICKE	25-50 μm
Sn Pb-THICKNESS ZINN/BLEI SCHICHTDICKE	4-15 μm
DRILLED HOLE Ø1.10±0.025 BOHRLOCH Ø1.10±0.025	FINISHED HOLE Ø0.94 ^{+0.15} _{-0.15} PLATIIERTER LOCH Ø0.94 ^{+0.15} _{-0.15}

A2

6

DIMENSION OF LOOSE PIECE

Mass fuer Einzelteil

7

ACCORDING TO EXECUTION INSTUCTION AUDI NO. N 905 854

Nach Ausfuehrungsvorschrift AUDI Nr. N 905 854

8

TO BE REELED ON PANCAKE REEL WITH INTERLEAVING PAPER

Pappspulen mit Zwischenlagenpapier

9

TO BE REELED ON PLASTIC REEL WITH INTERLEAVING PAPER

Kunststoffspulen mit Zwischenlagenpapier

10

0.8 μm - 2.0 μm Au

0.8 μm - 2.0 μm Au

DIRECTION OFF
TOP OF REEL

1-

2-

1-

3-

2-

2-

2-

-3

8

9

2-1823233-3	A	Cu Sn 4	2 + 10 OVER ueber 1	9
2-1823233-2	A	Cu Sn 4	2 + 10 OVER ueber 1	8
1-1823233-3	A	Cu Sn 4	2 + 3 + 4 OVER ueber 1	9
1-1823233-2	A	Cu Sn 4	2 + 3 + 4 OVER ueber 1	8
TE PART NO	REV.	MATERIAL	SURFACE	REEL PACKAGING

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN P. Nickelfeld CHK J. Ryll	30OCT2008 30OCT2008	TE Connectivity	
DIMENSIONS: mm		TOLERANCES UNLESS OTHERWISE SPECIFIED: Allgemeintoleranz n. ISO 8015 n. ISO 2768-MH-E		NAME	
		0-PLC ± 1-PLC ±0.2 2-PLC ±0.1 3-PLC ± 4-PLC ± ANGLES ±1°		PRODUCT SPEC	
MATERIAL		FINISH		APPLICATION SPEC	
-		-		108-18706	
-		-		114-18379	
CUSTOMER DRAWING				WEIGHT	-
SCALE 10:1				SHEET 1 OF 1	REV A2

1471-9 (3/13)